2SB955(K)

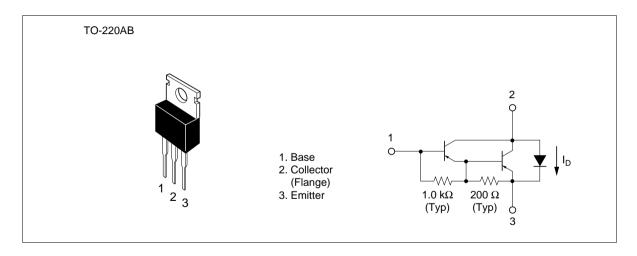
Silicon PNP Triple Diffused

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Application

Power switching complementary pair with 2SD1126(K)

Outline





2SB955(K)

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	-120	V
Collector to emitter voltage	V _{CEO}	-120	V
Emitter to base voltage	V _{EBO}	-7	V
Collector current	I _c	-10	A
Collector peak current	I _{C(peak)}	–15	A
C to E diode forward current	I _D *1	10	A
Collector power dissipation	P _c *2	50	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

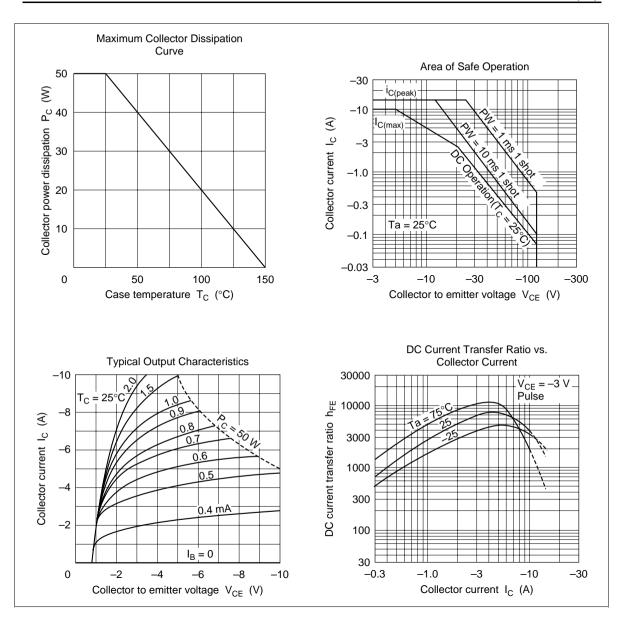
Notes: 1. Value at $T_c = 25^{\circ}C$

2. PW ≤ 1 ms 1 shot

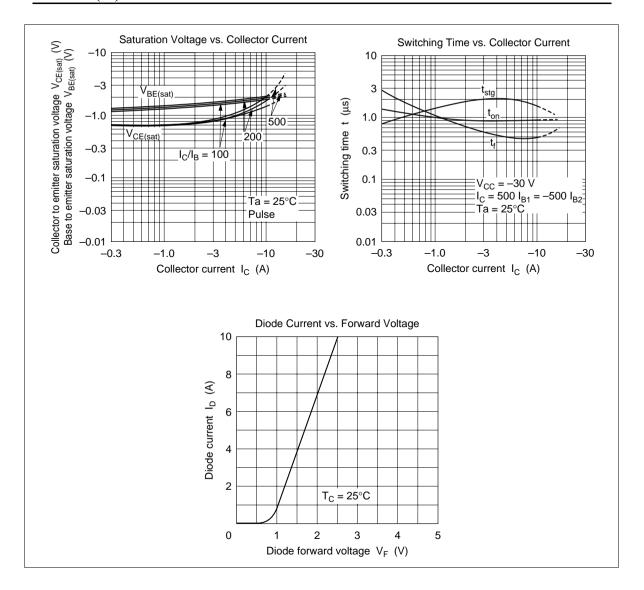
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-120	_	_	V	$I_{c} = -25 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-7	_	_	V	$I_{\rm E} = -200 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	-100	μΑ	$V_{CB} = -120 \text{ V}, I_{E} = 0$
	I _{CEO}	_	_	-10	μΑ	V _{CE} = −100 V, R _{BE} = ∞
DC current transfer ratio	h _{FE}	1000	_	20000		$V_{CE} = -3 \text{ V}, I_{C} = -5 \text{ A}^{*1}$
Collector to emitter saturation	$V_{\text{CE(sat)1}}$	_	_	-1.5	V	$I_{\rm C} = -5 \text{ A}, I_{\rm B} = -10 \text{ mA}^{*1}$
voltage	V _{CE(sat)2}	_	_	-3.0	V	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -0.1 \text{ A}^{*1}$
Base to emitter saturation	$V_{BE(sat)1}$	_	_	-2.0	V	$I_{\rm C} = -5 \text{ A}, I_{\rm B} = -10 \text{ mA}^{*1}$
voltage	$V_{BE(sat)2}$	_	_	-3.5	V	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -0.1 \text{ A}^{*1}$
C to E diode forward voltage	V _D	_	_	3.0	V	I _D = 10 A*1
Turn on time	t _{on}	_	0.8	_	μs	V _{cc} = -30 V
Turn off time	t _{off}	_	4.0	_	μs	$I_{\rm C} = -5 \text{ A}, I_{\rm B1} = -I_{\rm B2} = -10 \text{ mA}$

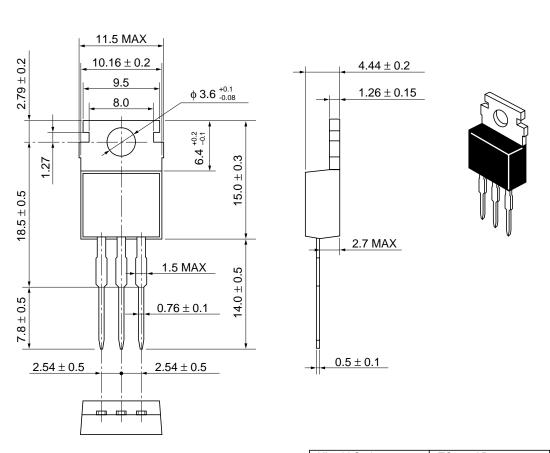
Note: 1. Pulse test



2SB955(K)



Unit: mm



Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.8 g

Cautions

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Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.

Electronic Components Group.

Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000

Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building. No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666

Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218

Fax: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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